

IN THE CLAIMS:

Please cancel claims 15-16, 19-20, and 24-28, and amend the claims as follows:

1-13 (Cancelled)

14. (Currently Amended) A method of forming a contact ring, comprising:
providing [[a]] an annular substrate;
depositing at least a first one conductive layer on the annular substrate, wherein
said first conductive layer coats a all support surface[[s]] of the annular substrate; [[and]]
depositing at least a first one insulative layer adjacent to the at least a first
conductive layer, on the annular substrate, wherein said first insulative layer coats all
surfaces of the substrate conductive layer; and
electrically connecting a contact to the conductive layer through said insulative
layer on the annular substrate.

15-16. (Cancelled)

17. (Currently Amended) The method of claim 14 [[16]], further comprising
~~electrically connecting a contact to at least one of the conductive layers, wherein the~~
~~depositing a compliant ridge extends around the periphery of that surrounds~~ the contact.

18. (Currently Amended) A contact ring for providing electrical contact between a
wafer and a power supply, comprising:
a conductive layer positioned on at least one support surface of an annular
substrate;
an insulative layer deposited above the conductive layer;
a contact in electrical contact with the conductive layer and extending through the
insulative layer above the conductive layer to an external surface; and
a compliant ridge formed on the external surface, and extending about the
periphery of the contact.

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19-28. (Cancelled)

Page 3

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PAGE 4/6 * RCVD AT 1/16/2004 7:50:33 PM [Eastern Standard Time] * SVR:USPTO-EFXRF-1/2 * DNIS:8729306 * CSID:+7136234846 * DURATION (mm:ss):01:20